

Ratings and Characteristics

Maximum Ratings, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC})	-0.5 to +6 V
DC INPUT DIODE CURRENT, I_{IK} (for $V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_O (for $V_O > -0.5$ V or $V_O < V_{CC} + 0.5$ V)	± 50 mA
DC V_{CC} or GROUND CURRENT (I_{CC} Or I_{GND})	± 100 mA*
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE F)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE F)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
OPERATING-TEMPERATURE RANGE (T_A):	
PACKAGE TYPE F	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

*(For up to 4 outputs per device, add ± 25 mA for each additional output.)

Recommended Operating Conditions:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} * (For $T_A =$ Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage V_I, V_O	0	V_{CC}	
Operating Temperature, T_A : CD54 Types	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dt/dv			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (AC Types)	0	10	ns/V

*Unless otherwise specified, all voltages are referenced to ground.